



The “**IEEE International conference on Physical Assurance and Inspection of Electronics**” ([PAINE](#)), is to be held on **October 27-29, 2026** at **Hyatt Regency - Phoenix, AZ**. Accepted papers will be published in IEEE Xplore after peer review by the PAINE TPC.

SCHEDULE

Full Paper (7 pages):	July 20, 2026
Notification of Acceptance:	August 17, 2026
Camera ready version:	September 7, 2026

PAINE 2025 winners: <https://paine-conference.org/>

Winners will receive their plaque during the PAINE 2026 opening

PAINE 2025 proceedings: <https://ieeexplore.ieee.org/xpl/conhome/11320137/proceeding>

Topics covered are including but not limited to:

- New metrologies for characterization and assurance
- Secure Heterogeneous Integration and Advanced Packaging
- Role of LLMs in Physical Assurance and Inspection
- Emerging topics in physical inspection and assurance
- Test vehicles and performance quantification
- Multi-modal Analysis
- Automated inspection and metrology for advanced packaging
- Additive manufacturing assurance for electronics
- Image analysis & artificial intelligence for assurance and inspection
- RadHard design and assessment
- Novel material and devices for assurance
- Forensic Analysis
- Sample Preparation for advanced node devices

- PCB trust and assurance
- Chip and PCB level decomposition for assurance
- Side channel assessment for assurance and countermeasures
- FIB/SEM for assurance
- Electro-optical probing using PEM, EOP, EOFM, etc.
- Physical/side channel fingerprinting
- Mod-chip on PCB
- Micro probing and nanoprobng
- Physical and design interface assurance
- Fault injection assessment and countermeasures
- Field-based weakness
- Countermeasures against tampering and decomposition
- Physical/logical shielding, etc.
- FPGA Bitstream protection and vulnerabilities
- Analog & mixed-signal circuits and systems security
- Security primitives: Novel devices, materials, and systems
- Trojans and backdoors: Detection and prevention
- Counterfeit Detection and Anti-Counterfeit Technique
- Inspection Structures for Assurance

This event is open to public; we encourage everyone from academia, industry, and government to attend.

[Sponsorship](#)

Sponsorship opportunities for the conference are available.

If interested, please contact the Program or General Chair